

□ MN101E13 Series

Type	MN101E13G	MN101EF13G
Internal ROM type	Mask ROM	FLASH
ROM (byte)	128K	
RAM (byte)	4K	
Package (Lead-free)	QFP084-P-1818E	QFP084-P-1818E (ES (Engineering Sample) available)
Minimum Instruction Execution Time	100 ns (at 3.135 V to 3.465 V, , normal-mode)	100 ns

■ Interrupts

External (7 lines)

Internal (13 lines) : Timer × 4, A/D × 1, RESET × 1, OSD × 1, Serial × 2, I²C × 1, Caption × 1, Remote control × 1, HSYNC × 1, VSYNC × 1

■ Timer Counter

8-bit timer × 4

Watchdog timer : Time-out period is selectable.

■ Serial interface

I²C × 1 : for multimaster mode, bus line (output) has 2 systems

Sync serial / UART × 1

■ Caption / Teletext Decoder

Built-in sync separator × 1

■ I/O Pins

I/O 35 : Common use

■ A/D converter

10-bit × 8-ch. (with S/H)

■ PWM

8-bit × 6-ch. , 14-bit × 1-ch.

■ Special Ports

Remote control reception

■ CRTC

1-layer display (graphics, characters, splits)

■ Notes

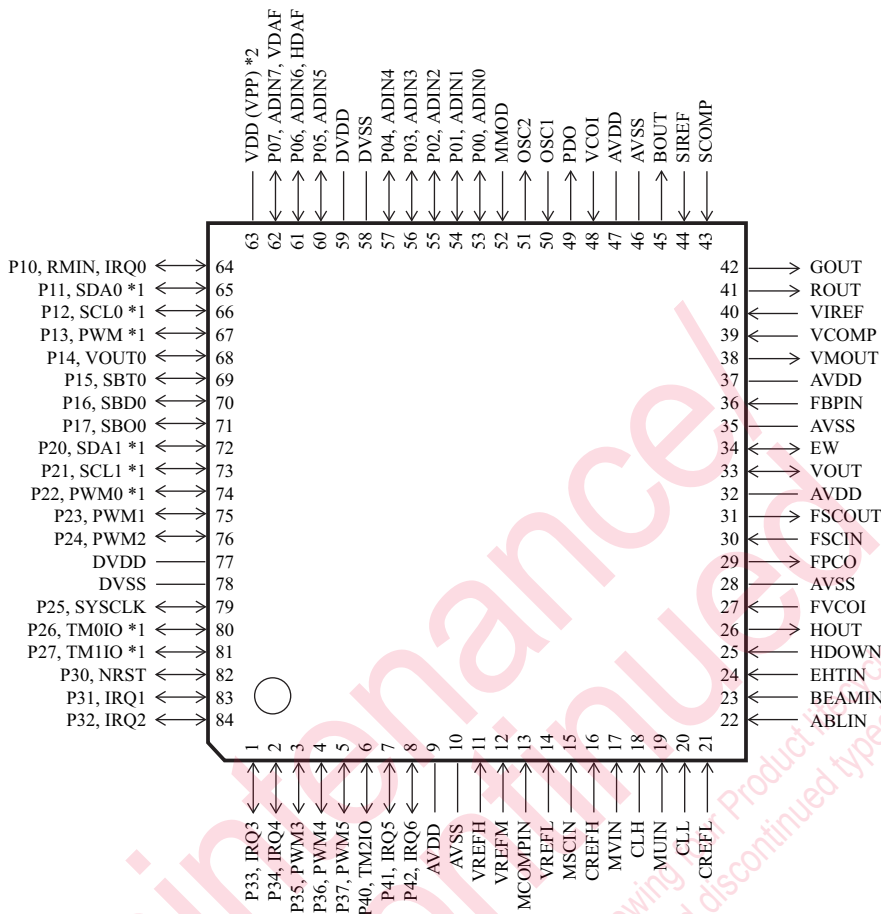
Remote control input discriminant circuit built-in, built-in NTSC video signal processing circuit, built-in 3-line comb filter

■ Development tools

In-circuit Emulator

PX-PAC101E02-4W9J

■ Pin Assignment
QFP084-P-1818E



Note) *1: 5 V dielectric N-ch. open drain output pin
*2: Mask ROM = VDD, Flash memory built-in type = VPP

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